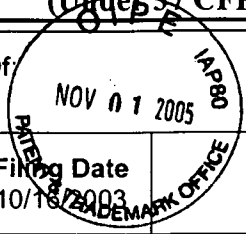


11-02-05

FFW

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT (Under 37 CFR 197(b) or 1.97(c))					Docket No. 15436.51.1	
In Re Application Of: Aronson, et al.						
Application No. 10/687,107	Filing Date 10/19/2003	Examiner unknown	Customer No 022913	Group Art Unit 2816	Confirmation No. 7228	
Title: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS CONNECTIONS TO OPTICAL SUBASSEMBLIES						



Address to:
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

37 CFR 1.97(b)

1. ☒ The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.

37 CFR 1.97(c)

2. ☐ The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:
- ☐ the statement specified in 37 CFR 1.97(e);
- OR**
- ☐ the fee set forth in 37 CFR 1.17(p).

TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT
(Under 37 CFR 197(b) or 1.97(c))

Docket No.
15436.51.1

In Re Application Of:

Aronson, et al.

Application No.	Filing Date	Examiner	Customer No	Group Art Unit	Confirmation No.
10/687,107	10/16/2003	unknown	022913	2816	7228

Title:
FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS CONNECTIONS TO OPTICAL SUBASSEMBLIES

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(Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))

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Kari W. Stange
Signature

Dated: 10/31/05

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Applicant(s): Aronson, et al.

Docket No.
15436.51.1Application No.
10/687,107Filing Date
10/16/2003Examiner
unknownCustomer No
022913Group Art Unit
2816

Invention:

FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS CONNECTIONS TO OPTICAL SUBASSEMBLIES

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Information Disclosure Statement (2 pages)

Information Disclosure Statement Transmittal (2 pages)

Information Disclosure Statement Citation (7 pages and 18 references attached)

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PATENT APPLICATION
Docket No: 15436.51.1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of)	
)	
	Aronson, et al.)	
)	
Serial No.:	10/687,107)	Art Unit
)	2816
Confirmation No.:	7228)	
)	
Filed:	October 16, 2003)	
)	
For:	FLEXIBLE CIRCUIT DESIGN FOR IMPROVED)	
	LASER BIAS CONNECTIONS TO OPTICAL)	
	SUBASSEMBLIES)	

INFORMATION DISCLOSURE STATEMENT
UNDER 37 C.F.R. § 1.97

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please find, pursuant to 37 C.F.R. § 1.98(a)(1), the enclosed Form PTO-1449 which contains a list of all patents, publications, or other items that have come to the attention of one or more of the individuals designated in 37 C.F.R. § 1.56(c). While no representation is made that any of these references may be "prior art" within the meaning of that term under 35 U.S.C. §§ 102 or 103, the enclosed list of references is disclosed so as to fully comply with the duty of disclosure set forth in 37 C.F.R. § 1.56.

Moreover, while no representation is made that a specific search of office files or patent office records has been conducted or that no better art exists, the undersigned attorney of record

believes that the enclosed art is the closest to the claimed invention (taken in its entirety) of which the undersigned is presently aware, and no art which is closer to the claimed invention (taken in its entirety) has been knowingly withheld.

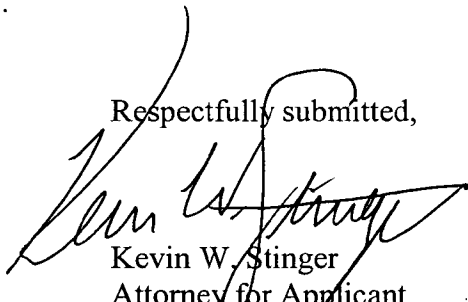
The accompanying Form PTO-1449 notifies the Examiner of the specified related pending U.S. patent applications listed therein. This notice is not an admission that the claims of the present application and the claims of the specified related pending patent applications are substantially similar or that the specified related applications represent prior art with respect to the present application.

In accordance with 37 C.F.R. §§ 1.97 and 1.98, a copy of the listed non-U.S. patent references or relevant portion thereof is also enclosed.

This Information Disclosure Statement is being filed before a first Office Action on the merits has been received, therefore, no fee is believed to be due. Please credit any over payment or charge any additional fees to Deposit Account No. 23-3178 of the undersigned.

DATED October 31, 2005.

Respectfully submitted,



Kevin W. Stinger
Attorney for Applicant
Registration No. 48,959
Customer No. 022913

KWS: gj
gh0000000541V001

Applicant: Argenson, et al.

Serial No. 10/687,107

Att'y Docket No.: 15436.51.1

Filing Date: October 16, 2003

Group: 2816

For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
CONNECTIONS TO OPTICAL SUBASSEMBLIESINFORMATION DISCLOSURE CITATIONS MADE BY APPLICANTRelated U.S. Patent Applications

	<u>Inventor</u>	<u>Application Number</u>	<u>Filing Date</u>
<u>/D.T./</u> 1	Kumar, et al.	10/409,837	04/09/2003
2	Kumar, et al.	10/835,832	04/30/2004
3	Ellison	10/836,728	04/30/2004
4	Liu, et al.	11/094,990	03/31/2005
5	Ice, Donald A.	11/179,223	07/11/2005
6	Nippa, et al.	10/836,129	04/30/2004

U.S. Patent Documents

<u>Examiner Initial*</u>	<u>Document Number</u>	<u>Issue/Pub Date</u>	<u>Name</u>
<u>/D.T./</u> 7	3,271,214	09/06/1966	Tabor
8	3,987,676	10/26/1976	Bennewitz
9	4,092,061	05/30/1978	Stigliani, Jr.
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12	4,769,684	09/06/1988	Crocker, et al.
13	4,818,099	04/04/1989	Preikschat, et al.

Examiner: /Dzung Tran/

Date Considered:

02/06/2009

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609, draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Applicant: Aronson, et al.

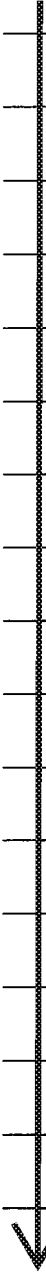

Serial No.: 10/687,107

Att'y Docket No.: 15436.51.1

Filing Date: October 16, 2003

Group: 2816

For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
CONNECTIONS TO OPTICAL SUBASSEMBLIES

/D.T./	14	4,952,016	08/28/1990	Adams, et al.
	15	4,962,991	10/16/1990	Carvalho
	16	5,125,054	06/23/1992	Ackley, et al.
	17	5,136,682	08/04/1992	Moyer, et al.
	18	5,212,345	05/18/1993	Gutierrez
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	25	5,371,822	12/06/1994	Horwitz, et al.
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	27	5,389,686	02/14/1995	Diop, et al.
	28	5,414,786	05/19/1995	Ohta, et al.
	29	5,420,954	05/30/1995	Swirhun, et al.
	30	5,432,630	07/11/1995	Lebby, et al.
	31	5,471,552	11/28/1995	Wuu, et al.
	32	5,495,125	02/27/1996	Uemura

Examiner: /Dzung Tran/

Date Considered: 02/06/2009

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Applicant: Aronson, et al.



Serial No.: 10/687,107

Att'y Docket No.: 15436.51.1

Filing Date: October 16, 2003

Group: 2816

For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
CONNECTIONS TO OPTICAL SUBASSEMBLIES

/D.T./	33	5,499,312	03/12/1996	Hahn, et al.
	34	5,539,848	07/23/1996	Galloway
	35	5,545,846	08/13/1996	Williams, et al.
	36	5,596,662	01/21/1997	Boscher
	37	5,613,024	03/18/1997	Shahid
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	39	5,638,469	06/10/1997	Feldman, et al.
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	44	5,774,614	06/30/1998	Gilliland, et al.
	45	5,894,409	04/13/1999	Tanaka
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	51	6,088,498	07/11/2000	Hibbs-Brenner, et al.

Examiner: /Dzung Tran/

Date Considered:

02/06/2009

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Applicant: Aronson, et al.
 Serial No.: 10/687,107
 Filing Date: October 16, 2003
 For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
 CONNECTIONS TO OPTICAL SUBASSEMBLIES

Att'y Docket No.: 15436.51.1
 Group: 2816

/D.T./	52	6,091,475	07/18/2000	Ogino, et al.
	53	6,118,666	09/12/2000	Aoki, et al.
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	68	2003/0197254	10/23/2003	Huang
	69	2004/0090620	05/13/2004	Farr
	70	2004/0018409	01/29/2004	Hui, et al.

Examiner: /Dzung Tran/

Date Considered:

02/06/2009

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Applicant: Aronson, et al.
 Serial No.: 10/687,107 Att'y Docket No.: 15436.51.1
 Filing Date: October 16, 2003 Group: 2816
 For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
 CONNECTIONS TO OPTICAL SUBASSEMBLIES

<u>/D.T./</u> 71	2004/0062491	04/01/2004	Sato, et al.
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Foreign Patent Documents

<u>Examiner Initial*</u>	<u>Document Number</u>	<u>Publication Date</u>	<u>Country or Patent Office</u>
<u>/D.T./</u> 73	0 905 838	03/31/1999	Great Britain
<u>74</u>	0 881 671	12/02/1998	Great Britain
<u>75</u>	09-223848	08/26/1997	Japan
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<u>78</u>	JP407159636	06/23/1995	Japan
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Other Documents

(including author, title, pertinent pages, etc.)

Examiner
Initial*

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Examiner:	/Dzung Tran/	Date Considered:	02/06/2009
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Applicant: Aronson, et al.

Serial No.: 10/687,107

Att'y Docket No.: 15436.51.1

Filing Date: October 16, 2003

Group: 2816

For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
CONNECTIONS TO OPTICAL SUBASSEMBLIES

- /D.T./
- 81 ALI, "New Materials and Design Components for Integrated Optics," Technology Report/Fiberoptics, LASER FOCUS WORLD, Vol. 21, No. 8, August 1985, Tulsa, U.S., pp 48-50
- 82 COHEN, "Passive Laser-Fiber Alignment by Index Method," IEEE Photonics Technology Letters, Vol. 3, No. 11, December 1991, pp 985-987, New York, U.S.
- 83 COLDREN, et al., "Flip-Chip Bonded, Back-Emitting, Microlensed Arrays of Monolithic Vertical Cavity Lasers and Resonant Photodetectors," Electronic Components and Technology Conference, Sept. 1999, pp. 733-740
- 84 HAVANT, "Flexible Interposing Carrier Scheme for Optical Waveguides," Research Disclosure No. 303, July 1989, page 512
- 85 HIBBS-BRENNER, et al., "Packaging of VCSEL Arrays for Cost-Effective Interconnects at <10 Meters," Electronic Components and Technology Conference, Sept. 1999, pp. 747-752
- 86 HSU, et al., "Flip-chip Approach to Endfire Coupling Between Single-Mode Optical Fibres and Channel Waveguides," Patent Associates Literature, Electronic Letters, Vol. 12, No. 16, pp. 404-405, 08/05/1976
- 87 KAZLAS, et al., "Monolithic Vertical-Cavity Laser/p-i-n Photodiode Transceiver Array for Optical Interconnects," IEEE Photonics Technology Letters, Nov. 1998, pp. 1530-1532, Vol. 10, No. 11.
- 88 LOUDERBACK, et al., "Flip Chip Bonded Arrays of Monolithically Integrated, Microlensed Vertical-Cavity Lasers and Resonant Photodetectors," IEEE Photonics Technology Letters, March 1999, pp. 304-306, Vol. II, No. 3.
- 89 PLAWSKY, et al., "Photochemically Machined, Glass Ceramic, Optical Fiber Interconnection Components," Article, Optoelectronic Materials, Devices, Packaging and Interconnects (1998), SPIE, Vol. 994, pp. 101-106
- 90 SULLIVAN, et al., "Polymeric Waveguides," 1992 IEEE, pp. 27-31

Examiner: /Dzung Tran/

Date Considered: 02/06/2009

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Applicant: Aronson, et al.
Serial No.: 10/687,107 Att'y Docket No.: 15436.51.1
Filing Date: October 16, 2003 Group: 2816
For: FLEXIBLE CIRCUIT DESIGN FOR IMPROVED LASER BIAS
CONNECTIONS TO OPTICAL SUBASSEMBLIES

References Cited by Applicants

While the filing of Information Disclosure Statements is voluntary, the procedure is governed by the guidelines of Section 609 of the Manual of Patent Examining Procedure and 37 C.F.R. §§ 1.97 and 1.98. To be considered a proper Information Disclosure Statement, Form PTO-1449 shall be accompanied by a copy of each listed patent or publication or other item of information and a translation of the pertinent portions of foreign documents (if an existing translation is readily available to the applicant), an explanation of relevance of each reference not in the English language, and should be submitted in a timely manner as set out in MPEP Sec. 609.

Examiners will consider all citations submitted in conformance with 37 C.F.R. § 1.98 and MPEP Sec. 609 and place their initials adjacent the citations in the spaces provided on this form. Examiners will also initial citations not in conformance with the guidelines which may have been considered. A reference may be considered by the Examiner for any reason whether or not the citation is in full conformance with the guidelines. A line will be drawn through a citation if it is not in conformance with the guidelines AND has not been considered. A copy of the submitted form, as reviewed by the Examiner, will be returned to the applicant with the next communication. The original of the form will be entered into the application file.

Each citation initialed by the Examiner will be printed on the issued patent in the same manner as references cited by the Examiner on Form PTO-892.

The reference designations "A1," "A2," etc. (referring to Applicant's reference 1, Applicant's reference 2, etc.) will be used by the Examiner in the same manner as Examiner's reference designations "A," "B," "C," etc. on Office Action Form PTO-1142.

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Examiner:	/Dzung Tran/	Date Considered:	02/06/2009
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